



## Materials Declaration Form

<b>IPC Form Type *</b>	1752 Distribute	<b>Version</b>	2
<b>Sectionals *</b>	Material Info Manufacturing Info	<b>Subsectionals *</b>	A-D <i>* : Required Field</i>

Supplier Information			
<b>Company Name *</b>	STMicroelectronics	<b>Response Date *</b>	2018-01-09
<b>Company Unique ID</b>	NL 008751171801		
<b>Contact Name *</b>	Refer to Supplier Comment section		Refer to Supplier Comment section
<b>Contact Phone *</b>	Refer to Supplier Comment section	<b>Contact Email *</b>	Refer to Supplier Comment section
<b>Authorized Representative *</b>	Floriana SAN BIAGIO	<b>Representative Title</b>	AMS MD CHAMPION
<b>Representative Phone *</b>	Refer to Supplier Comment section	<b>Representative Email *</b>	Refer to Supplier Comment section
<b>Supplier Comment</b>	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/web/en/support/support.html">http://www.st.com/web/en/support/support.html</a>		

**Uncertainty Statement**

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**Legal Statement**

<b>Supplier Acceptance *</b>	true	<b>Legal Declaration *</b>	Standard
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**Legal Statement**

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	MQCL*VBOCTE3	A	Z6HA	2018-01-09
Amount	UoM	Unit type	ST ECOPACK Grade	
2.27	mg	Each	ECOPACK® 2	
	Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant ( in each organic material)		

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable	Nickel/Palladium/Gold (Ni/Pd/Au)	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
QFN	1.6x1.2x0.4	8	flat	
Comment	Package: B035 XVDFPN 1.6X1.2X0.4 8L 0.4; MDF valid for LD56100DPU30R			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	TRUE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	FALSE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description

QueryList : REACH-7th July 2017				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	MQL*VB0CTE3				5000002.0	999562.0
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	M-011 Other inorganic materials	0.161	mg	supplier	die	Silicon (Si)	7440-21-3		0.144	mg	894410	63436
				supplier	metallization	Aluminium (Al)	7429-90-5		0.004	mg	24845	1762
				supplier	metallization	Titanium (Ti)	7440-32-6		0.001	mg	6211	441
				supplier	metallization	Tungsten (W)	7440-33-7		0.003	mg	18634	1322
				supplier	Passivation	Silicon Nitride	12033-89-5		0.001	mg	6211	441
				supplier	Passivation	Silicon Oxide	7631-86-9		0.008	mg	49689	3524
Leadframe	M-004 Copper and its alloys	0.785	mg	supplier	alloy	Copper (Cu)	7440-50-8		0.744	mg	947771	327753
				supplier	alloy	Silicon (Si)	7440-21-3		0.009	mg	11465	3965
				supplier	alloy	Magnesium (Mg)	7439-95-4		0.002	mg	2548	881
				supplier	metallization	Nickel (Ni)	7440-02-0		0.030	mg	38217	13216
Die attach	M-015 Other organic materials	0.009	mg	supplier	glue	Silver (Ag)	7440-22-4		0.009	mg	1000000	3965
Bonding wires	M-008 Precious metals	0.019	mg	supplier	wire	Gold (Au)	7440-57-5		0.019	mg	1000000	8370
Encapsulation	M-015 Other organic materials	1.295	mg	supplier	mold compound	Epoxy resin	29690-82-2		0.039	mg	30116	17181
				supplier	mold compound	Phenol resin	25068-38-6		0.039	mg	30116	17181
				supplier	mold compound	Silica (Amorphous) A	60676-86-0		1.039	mg	802317	457709
				supplier	mold compound	Silica (Amorphous) B	7631-86-9		0.175	mg	135135	77093
				supplier	mold compound	Carbon Black	1333-86-4		0.003	mg	2317	1322